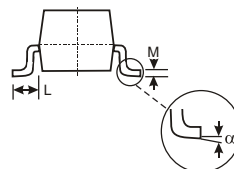
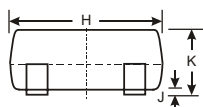
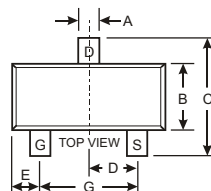


Features

- Super high density cell design for extremely low $R_{DS(ON)}$.
- Exceptional on-resistance and maximum DC current capability.
- We declare that the material of product compliance with RoHS requirements.



SOT-23		
Dim	Min	Max
A	0.37	0.51
B	1.20	1.40
C	2.30	2.50
D	0.89	1.03
E	0.45	0.60
G	1.78	2.05
H	2.80	3.00
J	0.013	0.10
K	0.903	1.10
L	0.45	0.61
M	0.085	0.180
α	0°	8°
All Dimensions in mm		

APPLICATIONS

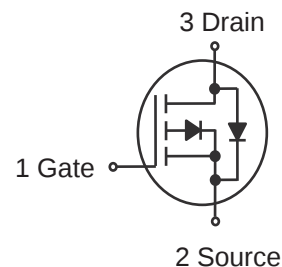
- Power Management in Notebook.
- Portable equipment.
- Battery powered system.
- Load switch.
- Marking Code:3401 OR A19T.

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current	I_D	-4.2	A
Peak Drain Current ¹⁾	I_{DM}	-18	A
Power Dissipation	P_D	0.90	W
Thermal Resistance from Junction to Ambient (PCB mounted) ²⁾	$R_{\theta JA}$	139	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 55 to + 150	$^\circ\text{C}$

¹⁾ Repetitive Rating: Pulse width limited by the Maximum junction temperature.

²⁾ 1 in² 2oz Cu PCB board.



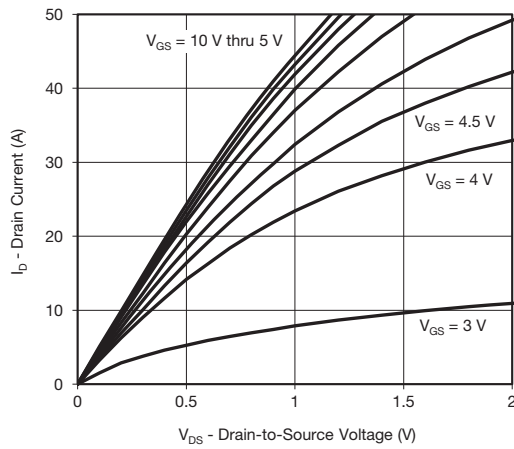
Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -30V, V_{GS} = 0V$			-1	μA
Gate-source leakage current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 100	nA
On characteristics						
Drain-source on-resistance (note 1)	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -4.2A$		45	60	m Ω
		$V_{GS} = -4.5V, I_D = -4A$		56	70	m Ω
		$V_{GS} = -2.5V, I_D = -1A$		69	95	m Ω
Forward tranconductance (note 1)	g_{FS}	$V_{DS} = -5V, I_D = -5A$		7		S
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.6	-0.9	-1.2	V
Dynamic characteristics (note 2)						
Input capacitance	C_{iss}	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$		1295		pF
Output capacitance	C_{oss}			150		pF
Reverse transfer capacitance	C_{rss}			130		pF
Switching characteristics (note 2)						
Turn-on delay time	$t_{d(on)}$	$V_{GS} = -10V, V_{DS} = -15V,$ $R_L = 3.6\Omega, R_{GEN} = 6\Omega$			20	ns
Turn-on rise time	t_r				8	ns
Turn-off delay time	$t_{d(off)}$				57	ns
Turn-off fall Time	t_f				12	ns
Drain-source diode characteristics and maximum ratings						
Diode forward voltage (note 1)	V_{SD}	$I_S = -4.2A, V_{GS} = 0V$			-1.2	V

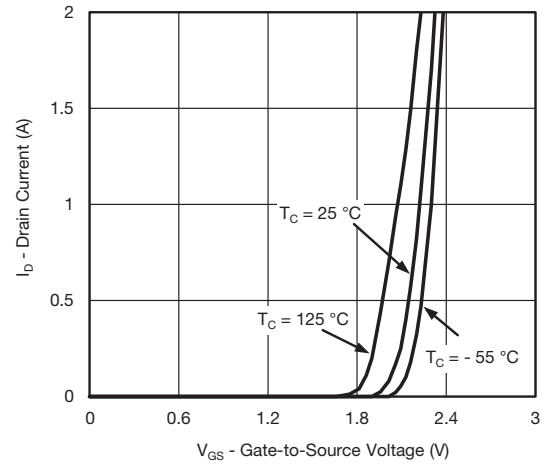
Note :

1. Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
2. These parameters have no way to verify.

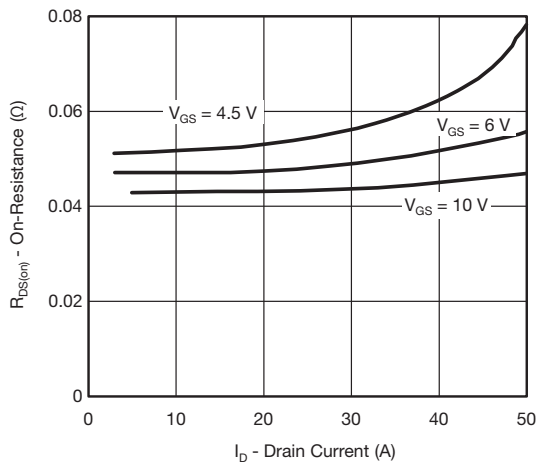
TYPICAL TRANSIENT CHARACTERISTICS



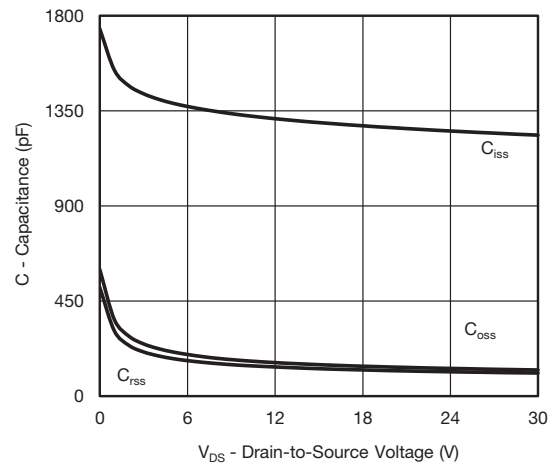
Output Characteristics



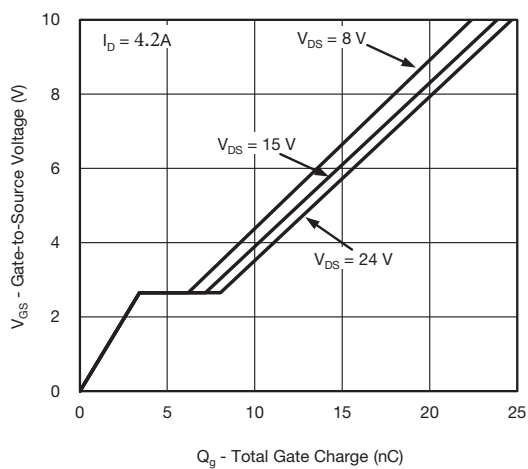
Transfer Characteristics



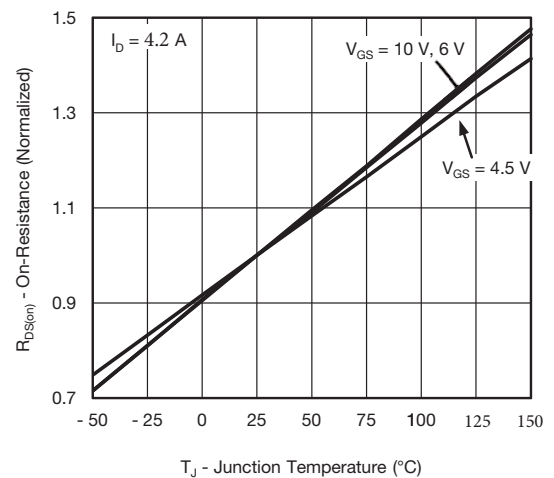
On-Resistance vs. Drain Current



Capacitance

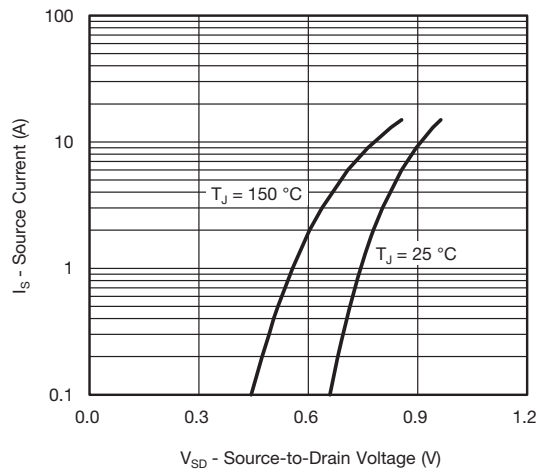


Gate Charge

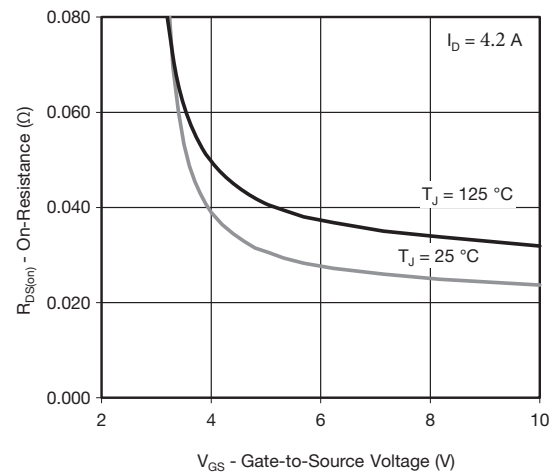


On-Resistance vs. Junction Temperature

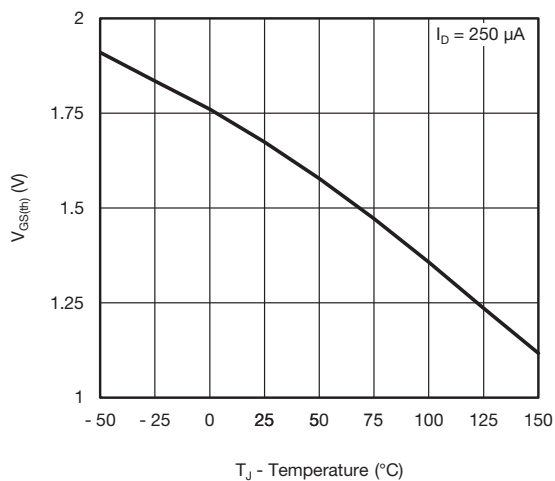
TYPICAL TRANSIENT CHARACTERISTICS



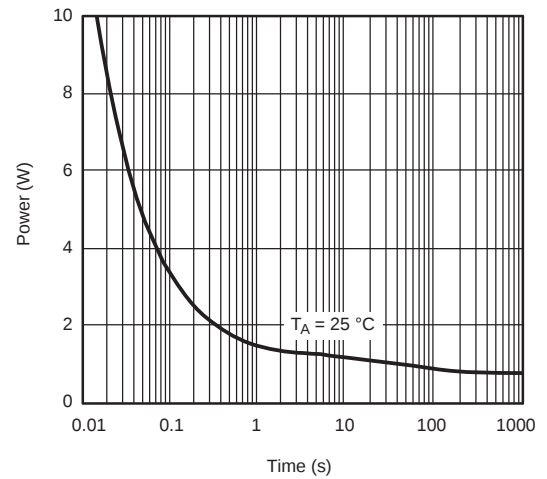
Source-Drain Diode Forward Voltage



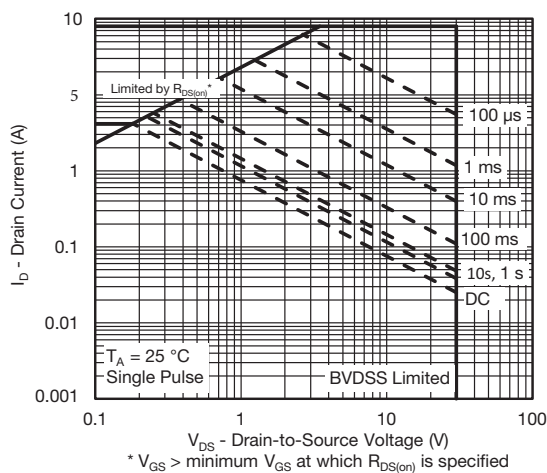
On-Resistance vs. Gate-to-Source Voltage



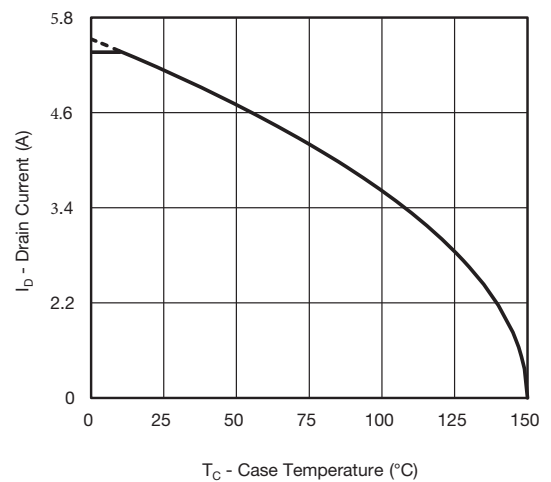
Threshold Voltage



Single Pulse Power (Junction-to-Ambient)

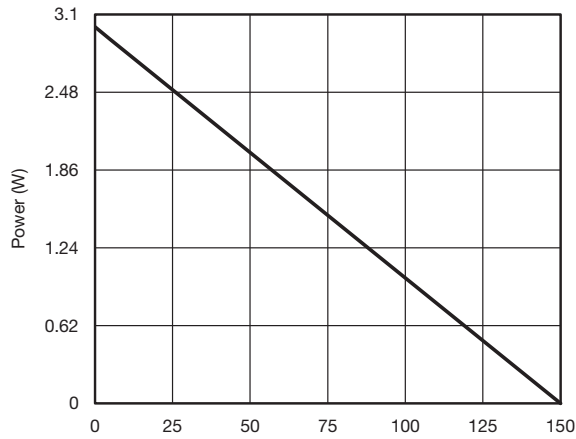


Safe Operating Area, Junction-to-Ambient

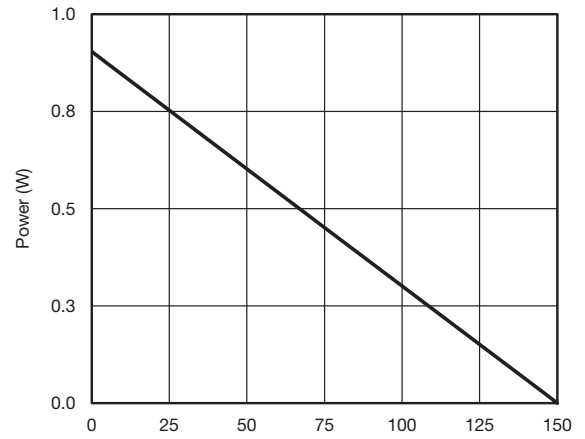


Current Derating*

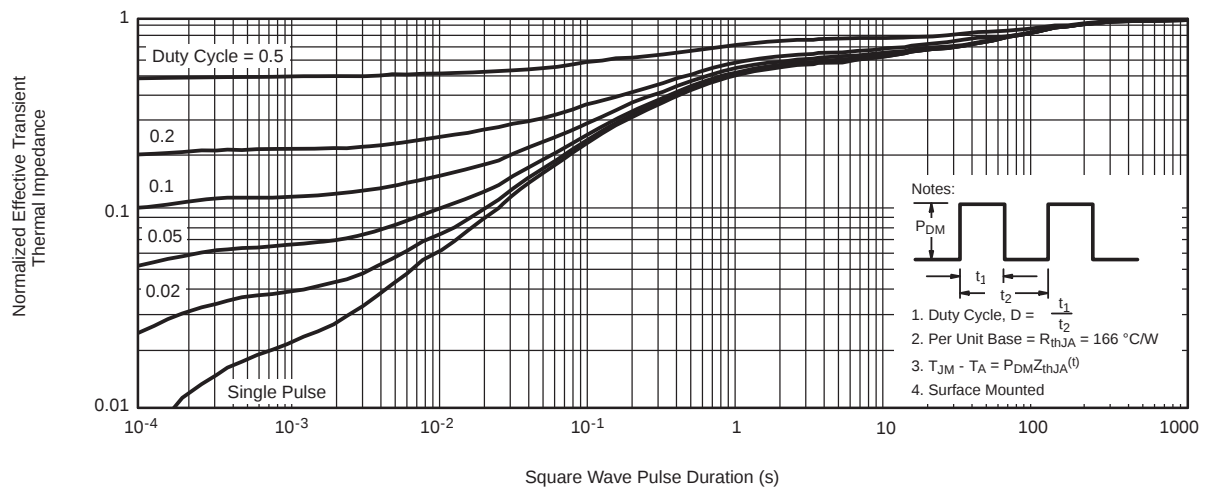
TYPICAL TRANSIENT CHARACTERISTICS



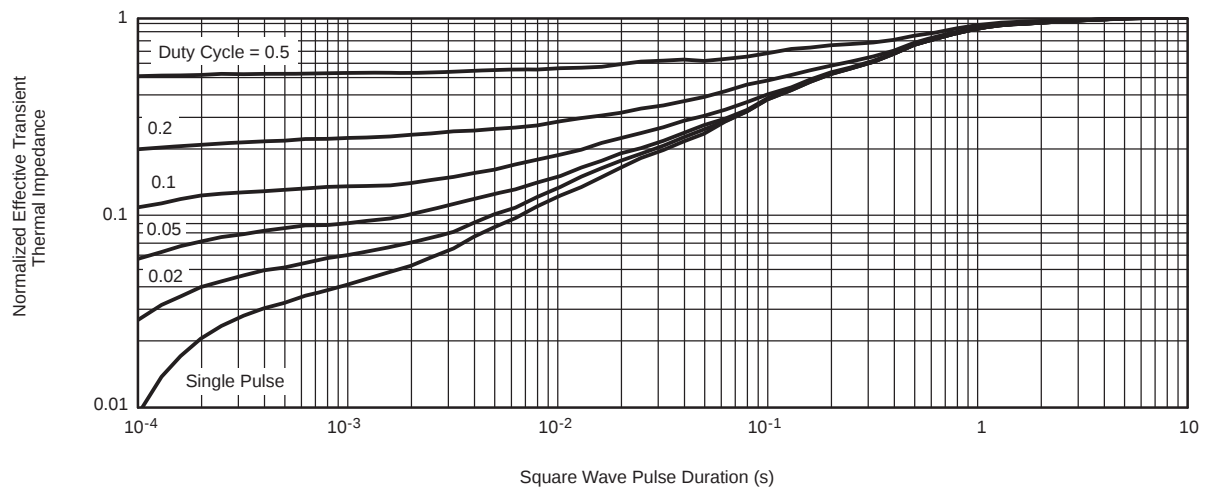
T_C - Case Temperature ($^{\circ}\text{C}$)
Power, Junction-to-Foot



T_A - Ambient Temperature ($^{\circ}\text{C}$)
Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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